ESD Protection Diodes Silicon Epitaxial Planar

# DF2S23P2CTC

#### 1. General

The DF2S23P2CTC is a TVS diode (ESD protection diode) protects semiconductor devices used in mobile device interfaces and other applications to protect against static electricity and noise.

The DF2S23P2CTC has realized high  $I_{PP}$ , in order to protect a semiconductor devices from the indirect lightning stroke and the transition voltage (at the time of power activation).

Furthermore, the DF2S23P2CTC is housed in an ultra-compact package (1.6 mm  $\times$  0.8 mm) to meet applications that require a small footprint.

#### 2. Applications

Mobile Equipment

- · Smartphones
- · Tablets
- · Notebook PCs

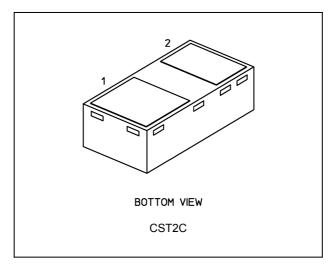
Desktop PCs

Note: This product is designed for protection against electrostatic discharge (ESD) and is not intended for any other purpose, including, but not limited to, voltage regulation.

#### 3. Features

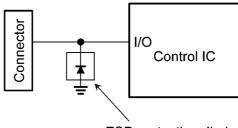
- (1) Suitable for use with a 20 V signal line. (V<sub>RWM</sub>  $\leq$  21 V)
- (2) Protects devices with its high ESD performance.  $(V_{ESD} = \pm 30 \text{ kV} (\text{Contact / Air}) @\text{IEC61000-4-2})$
- (3) Low dynamic resistance protects semiconductor devices from static electricity and noise.  $(R_{DYN} = 0.13 \Omega \text{ (typ.)})$
- (4) Snapback characteristics realizing low clamping voltage protects semiconductor devices.  $(V_C = 30 \text{ V}@I_{PP} = 14 \text{ A (typ.)})$
- (5) Compact package is suitable for use in high density board layouts such as in mobile devices.
   (1.6 mm × 0.8 mm size (Nickname: CST2C))

#### 4. Packaging



Start of commercial production 2018-04 2018-05-09 Rev.2.0

## 5. Example of Circuit Diagram



ESD protection diode

### 6. Quick Reference Data

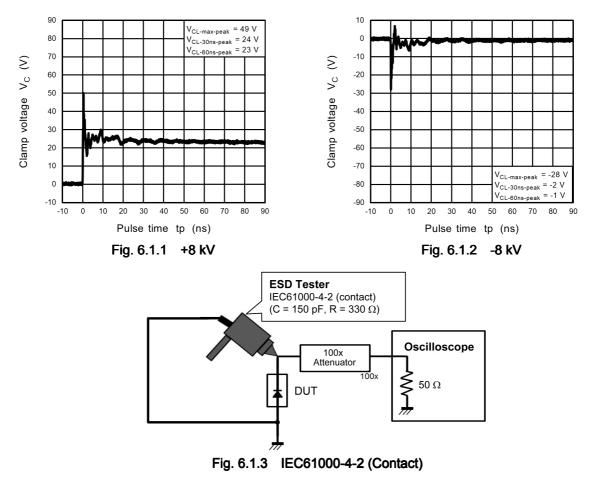
Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Working peak reverse voltage	V <sub>RWM</sub>	(Note 1)	_	_	_	21	V
Dynamic resistance	R <sub>DYN</sub>	(Note 2)	_	_	0.13	—	Ω
Electrostatic discharge voltage (IEC61000-4-2) (Contact)	$V_{ESD}$	(Note 3)	_			30	kV

Note 1: Recommended operating condition.

Note 2: TLP parameters:  $Z0 = 50 \Omega$ , tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP characteristics between  $I_{PP1} = 16$  A and  $I_{PP2} = 30$  A.

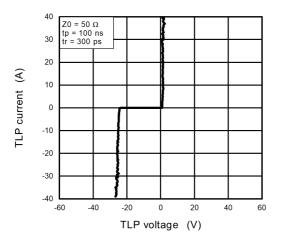
Note 3: Criterion: No damage to devices.

## 6.1. ESD Clamp Waveform (Note)



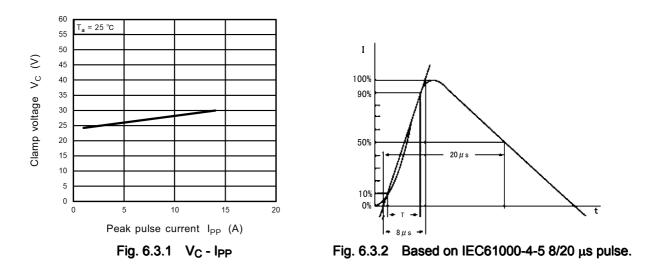
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

## 6.2. TLP Characteristics (Note)



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.





Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

## 7. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Note	Rating	Unit
Electrostatic discharge voltage (IEC61000-4-2) (Contact)	V <sub>ESD</sub>	(Note 1)	±30	kV
Electrostatic discharge voltage (IEC61000-4-2) (Air)			±30	
Peak pulse power (tp = 8/20 μs)	P <sub>PK</sub>		500	W
Peak pulse current (tp = 8/20 μs)	I <sub>PP</sub>	(Note 2)	14	А
Junction temperature	Tj		150	°C
Storage temperature	T <sub>stg</sub>		-55 to 150	C°

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

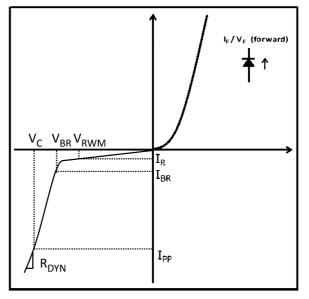
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: According to IEC61000-4-2.

Note 2: According to IEC61000-4-5.

### 8. Electrical Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

 $\label{eq:second} \begin{array}{l} V_{RWM} : \mbox{Working peak reverse voltage} \\ V_{BR} : \mbox{Reverse breakdown voltage} \\ I_{BR} : \mbox{Reverse breakdown current} \\ I_{R} : \mbox{Reverse current} \\ V_{C} : \mbox{Clamp voltage} \\ I_{PP} : \mbox{Peak pulse current} \\ R_{DYN} : \mbox{Dynamic resistance} \end{array}$ 



#### Fig. 8.1 Definitions of Electrical Characteristics

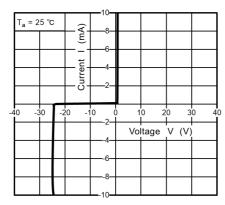
Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Working peak reverse voltage	V <sub>RWM</sub>	(Note 1)	_			21	V
Total capacitance	Ct		V <sub>R</sub> = 0 V, f = 1 MHz	_	160	_	pF
Dynamic resistance	R <sub>DYN</sub>	(Note 2)	—	_	0.13	_	Ω
Reverse breakdown voltage	V <sub>BR</sub>		I <sub>BR</sub> = 1 mA	21.5	24.1	25.5	V
Reverse current	I <sub>R</sub>		V <sub>RWM</sub> = 21 V		_	0.1	μA
Clamp voltage	V <sub>C</sub>	(Note 3)	I <sub>PP</sub> = 1 A		24.2		V
			I <sub>PP</sub> = 14 A	_	30	35.7	
		(Note 2)	I <sub>TLP</sub> = 16 A		25.5		V
			I <sub>TLP</sub> = 30 A		27.3	_	

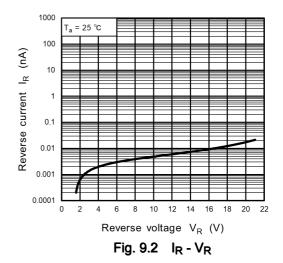
Note 1: Recommended operating condition.

Note 2: TLP parameters: Z0 = 50  $\Omega$ , tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP characteristics between I<sub>PP1</sub> = 16 A and I<sub>PP2</sub> = 30 A.

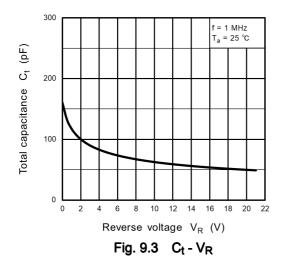
Note 3: Based on IEC61000-4-5 8/20 µs pulse.

## 9. Characteristics Curves (Note)





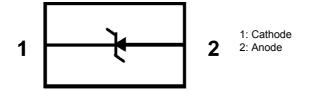




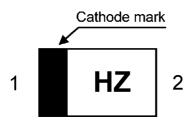
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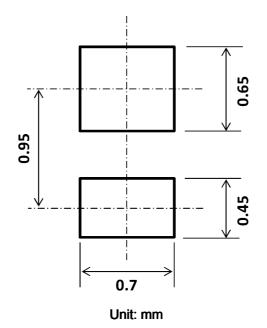
### 10. Internal Circuit



## 11. Marking (Top view)



## 12. Land Pattern Dimensions (for reference only)

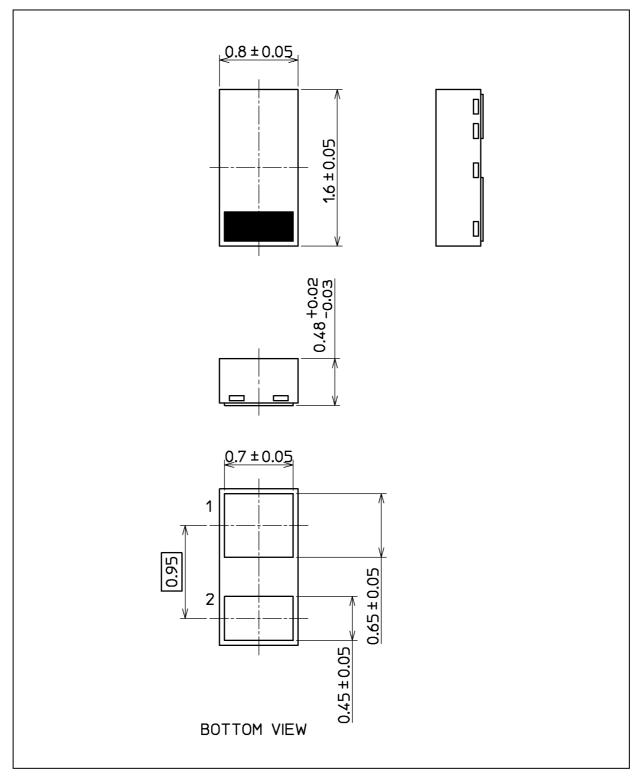




## DF2S23P2CTC

#### **Package Dimensions**

Unit: mm



Weight: 1.5 mg (typ.)

#### Package Name(s)

Nickname: CST2C

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